

UHV Technologies, Inc. introduces In-Situ Stress Measurement Instrumentation for thin film deposition systems

MUST-HAVE Instrument for Thin film process Uniformity and Repeatability

- * Retrofittable in Existing Systems
- * Water Cooled Miniature Sensor
- * 1 MPA to 10 GPa Range
- * Both Compressive and Tensile
- * Process End Point Detection

Ideal for

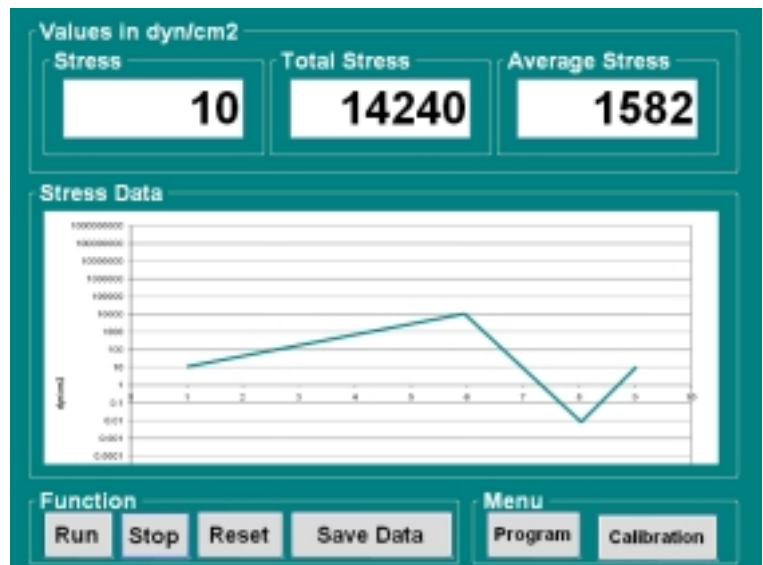
- * Thin Film R & D
- * Thin Film Manufacturing
- * Metal Thin Films
- * Oxide/Nitride Thin Films
- * MEMS
- * Semiconductors
- * Optoelectronics
- * Optical Coatings
- * Hard & Decorative Coatings
- * Automotive
- * Specialized Applications

FEATURES

- * 19 inch rack mountable
 - * Flat panel AMLCD touch screen
 - * Pentium PC based electronics
 - * Process end point detection capability
 - * 4 process set points
 - * Stress strips made from glass, silicon, plastic and metal are available
- ** Patents Pending**



Available
July '07



CAN BE USED WITH:

- * Arc, Thermal & E-Beam Evaporation
- * Pulsed Laser Deposition (PLD)
- * DC and RF Multi-Source Bias Sputtering
- * Ion Beam Deposition (IBD)
- * Atomic Layer epitaxy (ALE)
- * Plasma Enhanced CVD (PECVD)
- * Plasma and Reactive Ion Etching (RIE)